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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/620,714	07/15/2003	2833	1254	108298532US1	3	34	6

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CONFIRMATION NO. 9586

FILING RECEIPT

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Applicant(s)

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Domestic Priority data as claimed by applicant

This application is a DIV of 09/644,766 08/23/2000 PAT 6,607,937

Foreign Applications

If Required, Foreign Filing License Granted: 10/15/2003

Projected Publication Date: 01/22/2004

Non-Publication Request: No

Early Publication Request: No

Title

Stacked microelectronic dies and methods for stacking microelectronic dies

Preliminary Class